

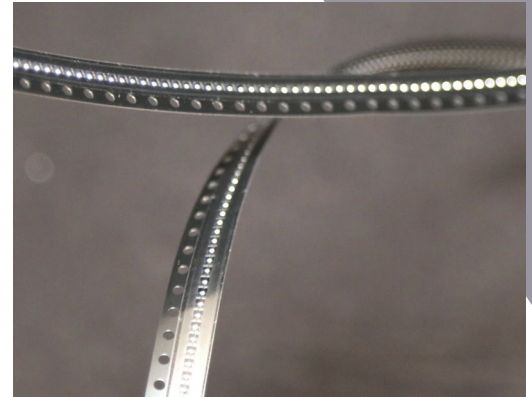
SNAPSHOT[®]

EMI SHIELD

SOLDER SPHERES IN TAPE AND REEL

To facilitate the use of XGRTM SnapShot[®] EMI Shield on your products, we provide solder spheres in tape and reel for use during fabrication of your boards. Solder spheres packaged in this manner can be used on standard SMT equipment. The materials are provided in a manner described by the following characterization chart:

Characterization Chart	
XGR P/N	1018470
Composition	96.5Sn/3.5Ag
Diameter	0.035" (0.889mm)
Dia. Tolerance	+/-0.0015" (0.038mm)
Spheres/Reel	20,000
Tape and Reel Std	EIA 481
Tape Width	8mm
Tape Pitch	2mm
Reel Diameter	13"



The solder spheres as provided by the bulk sphere supplier adhere to the JSTD006 No Lead standard and are inspected for composition to the following limits:

Alloy: 96.5Sn / 3.5Ag Specification: J-STD-006 No Lead			
Element	Inspect to	Element	Inspect to
Sn	Balance	Cd	0.002 Max
Pb	0.1 Max	Cu	0.005 Max
Sb	0.05 Max	Fe	0.02 Max
Ag	3.8 - 4.2	In	0.1 Max
Al	0.005 Max	Ni	0.01 Max
As	0.03 Max	Zn	0.001 Max
Bi	0.03 Max	Au	0.05 Max

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In November 2018 XGR Technologies acquired the SnapShot EMI Shielding business and assets from W.L. Gore & Associates. XGR manufactures SnapShot shields on the same equipment with the same people that made the SnapShot shields for W.L. Gore & Associates. XGR Technologies was founded and is run by one of the SnapShot patent holders.

*This testing was done by W.L. Gore & Associates prior to the asset transfer to XGR Technologies.

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